



951 Soldering Flux

Low-Solids No-Clean Liquid Flux

Product Description

Kester 951 is a halogen-free flux designed for wave soldering conventional and surface mount circuit board assemblies. The extremely low solids content (2.0%) and nature of the activator system results in practically NO RESIDUE left on the assembly after soldering. Boards are dry and cosmetically clean as they exit the wave solder machine. There are no residues to interfere with electrical testing. 951 exhibits improved soldering performance to minimize solder bridges (shorts) and excessive solder defects. This flux is suitable for automotive, computer, telecommunications and other applications where reliability considerations are critical. 951 contains a corrosion inhibitor such that no corrosion products are formed when bare copper surfaces are exposed to humid environments.

Performance Characteristics:

- Improves soldering performance
- Eliminates the need and expense of cleaning
- Non-corrosive tack-free residues
- Compliant to GR-78-CORE
- Classified as ORL0 per J-STD-004

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

Physical Properties

Specific Gravity: 0.814
Anton Paar DMA @ 25°C

Acid Number (typical): 14.3 mg
KOH/g flux
Tested by potentiometric titration

Thinner: 110

Percent Solids (theoretical): 2.0%

Reliability Properties

Copper Mirror Corrosion: Low
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Chloride and Bromides: None
Detected
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

SIR, IPC (typical): Pass
Tested to J-STD-004, IPC-TM-650, Method 2.6.3

Corrosion Test: Low
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Fluorides by Spot Test: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

| | Blank | 951PD | 951PU |
|-------|--------------------------|-------------------------|-------------------------|
| Day 1 | 2.3 × 10 ¹⁰ Ω | 9.4 × 10 ⁹ Ω | 8.2 × 10 ⁹ Ω |
| Day 4 | 1.3 × 10 ¹⁰ Ω | 7.8 × 10 ⁹ Ω | 7.5 × 10 ⁹ Ω |
| Day 7 | 9.8 × 10 ⁹ Ω | 6.3 × 10 ⁹ Ω | 5.8 × 10 ⁹ Ω |

Silver Chromate: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Flux Application

951 can be applied to circuit boards by a spray, foam or dip process. Flux deposition should be 120-240 mg of solids/cm² (750-1500 mg of solids/in²). An air knife after the flux tank is recommended to remove excess flux from the circuit board and prevent dripping on the preheater surface when used in a foam or wave application.

Process Considerations

The optimum preheat temperature for most circuit assemblies is 93-115°C (200-230°F) as measured on the top or component side of the printed circuit board. Dwell time in the wave is typically 2-4 seconds for leaded alloys and 4-8 seconds for lead-free alloys. The conveyor speed should be adjusted to accomplish proper board contact time with the solder. Then the preheat temperatures are adjusted to achieve the required preheat top board temperatures. In the event you need further direction on the setup of your wave soldering system, please contact Kester Technical Support.

Flux Control

Acid number is normally the most reliable method to control the flux concentration of low solids, no-clean fluxes. To check concentration, a simple acid-base titration should be used. PS-22 Test Kit and procedure are available from Kester. Control of the flux in the foam flux tank during use is necessary for assurance of consistent flux distribution on the circuit boards. The complex nature of the solvent system for the flux makes it imperative that Kester 110 Thinner be used to replace evaporative losses. When excessive debris from circuit boards, such as board fibers and from the air line build up in the flux tank, these particulates will redeposit on the circuit boards which may create a build up of residues on probe test pins. It is, therefore, necessary to clean the tank and then replenish it with fresh flux when excessive debris accumulates in the flux tank.

Cleaning

951 flux residues are non-conductive, non-corrosive and do not require removal in most applications. If residue removal is required, call Kester Technical Support.

Storage, Handling and Shelf Life

951 is flammable. Store away from sources of ignition. Shelf life is 1 year from the date of manufacture when handled properly and held at 10-25°C (50-77°F). The cap must be in place when not being used.

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product.

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